

FlipChip International Appoints Ted Tessier as Chief Technical Officer

PHOENIX, Arizona, June 28, 2006--FlipChip International LLC announced today that it has appointed Ted Tessier as Chief Technical Officer for its semiconductor wafer scale packaging and bumping business in Phoenix, Arizona. Ted joined FCI in 2005 as its Sr. Vice President of Engineering and Ted's background includes over 20 years of senior management experience in flip chip packaging, wafer level and 3-D packaging. In this position, Ted will direct the strategic activities of technology and product roadmaps, Research & Development, Intellectual Property portfolio management and continue in his role of leading FCI's product engineering efforts.

He has held significant leadership roles at STATS ChipPAC, Amkor Technology, Biotronik, Motorola and Bell Northern Research. Ted has a Master's degree in Applied Polymer chemistry from the University of Ottawa and is a senior member of the IMAPS organization. Ted is a well known authority in the industry and is a past recipient of the IMAPS John Wagnon technical achievement award.

Dr. Joan Vrtis, Chief Science Officer of FlipChip International said, "Ted is certainly a global leader in packaging technology in all respects and we are very excited for Ted to assume the critical position of CTO. FCI is fortunate to have his product development experience combined with his vision of the future as we roll out innovative new solutions for our customers' end products"

Bob Forcier, President and CEO of FlipChip International, stated, "Ted is an outstanding technologist with an excellent business background. Ted will be a key player in our high growth plans for our bumping fabs and our customers' growing needs for advanced flip chip, wafer level and 3D packaging solutions for their products."

FlipChip International, LLC is privately held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. Flip Chip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets.

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